AUTOMOTIVE GRADE

COMPLIANT

HALOGEN FREE



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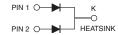
Vishay General Semiconductor

High Current Density Surface-Mount TMBS® (Trench MOS Barrier Schottky) Rectifier

Ultra Low $V_F = 0.36 \text{ V}$ at $I_F = 2.5 \text{ A}$







LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS				
I _{F(AV)}	2 x 5 A			
V _{RRM}	60 V			
I _{FSM}	80 A			
V_F at $I_F = 5$ A ($T_J = 125$ °C)	0.48 V			
T _J max.	150 °C			
Package	SlimDPAK (TO-252AE)			
Circuit configuration	Common cathode			

FEATURES

- Very low profile typical height of 1.3 mm
- Trench MOS Schottky technology
- · Ideal for automated placement
- · Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
 - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

TYPICAL APPLICATIONS

For use in low voltage high frequency DC/DC converters, freewheeling diodes, and polarity protection applications.

MECHANICAL DATA

Case: SlimDPAK (TO-252AE)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and

AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)				
PARAMETER		SYMBOL	V10PWL63C	UNIT
Device marking code		V10PWL63C		
Maximum repetitive peak reverse voltage	V_{RRM}	60	V	
Maximum average forward rectified current (Fig. 1)	per device	I _{F(AV)} (1)	10	А
	per diode		5	Α
Peak forward surge current 8.3 ms single half sine-was uperimposed on rated load per diode	I _{FSM}	80	А	
Operating junction temperature range	T _J ⁽²⁾	-40 to +150	°C	
Storage temperature range	T _{STG}	-55 to +150	°C	

Notes

⁽¹⁾ With infinite heatsink

 $^{^{(2)}}$ The heat generated must be less than the thermal conductivity from junction to ambient: $dP_D/dT_J < 1/R_{\theta JA}$



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ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	I _F = 2.5 A	$I_F = 2.5 \text{ A}$ $I_F = 5 \text{ A}$ $T_J = 25 \text{ °C}$	V _F ⁽¹⁾	0.45	-	V
	I _F = 5 A			0.52	0.60	
	I _F = 2.5 A	T _J = 125 °C		0.36	-	
	I _F = 5 A			0.48	0.55	
Reverse current per diode	$V_R = 60 \text{ V}$ $T_J = 25 \text{ °C}$ $T_J = 125 \text{ °C}$	T _J = 25 °C	I _R ⁽²⁾	-	0.08	mA
		T _J = 125 °C		4	9	
Typical junction capacitance per diode	4.0 V, 1 MHz		CJ	740	-	pF

Notes

 $^{(1)}\,$ Pulse test: 300 μs pulse width, 1 % duty cycle

 $^{(2)}\,$ Pulse test: pulse width $\leq 5\,$ ms

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	V10PWL63C	UNIT		
Typical thermal resistance per device	R ₀ JA (1)(2)	65	°C/W		
Typical thermal resistance per device	R _{0JM} (3)	2.1	C/VV		

Notes

- $^{(1)}$ The heat generated must be less than thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
- $^{(2)}$ Free air, mounted on recommended copper pad area; thermal resistance $R_{\theta JA}$ junction to ambient
- $^{(3)}$ Mounted on infinite heat sink; thermal resistance $R_{\theta JM}$ junction-to-mount

ORDERING INFORMATION (Example)					
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE	
V10PWL63C-M3/I	0.20	I	4500	13" diameter plastic tape and reel	
V10PWL63CHM3/I (1)	0.20	I	4500	13" diameter plastic tape and reel	

Note

(1) AEC-Q101 qualified



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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

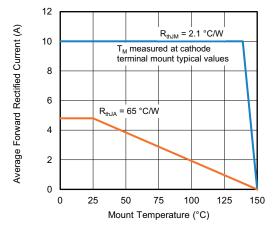


Fig. 1 - Maximum Forward Current Derating Curve

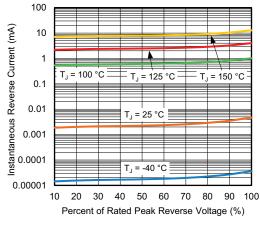


Fig. 4 - Typical Reverse Leakage Characteristics Per Diode

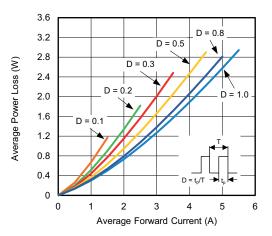


Fig. 2 - Forward Power Loss Characteristics Per Diode

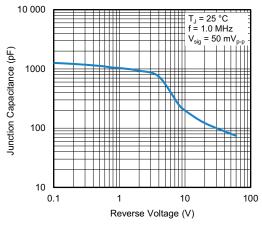


Fig. 5 - Typical Junction Capacitance Per Diode

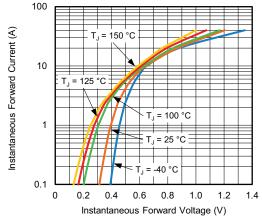


Fig. 3 - Typical Instantaneous Forward Characteristics Per Diode

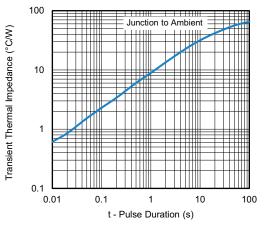


Fig. 6 - Typical Transient Thermal Impedance

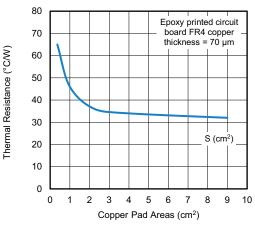
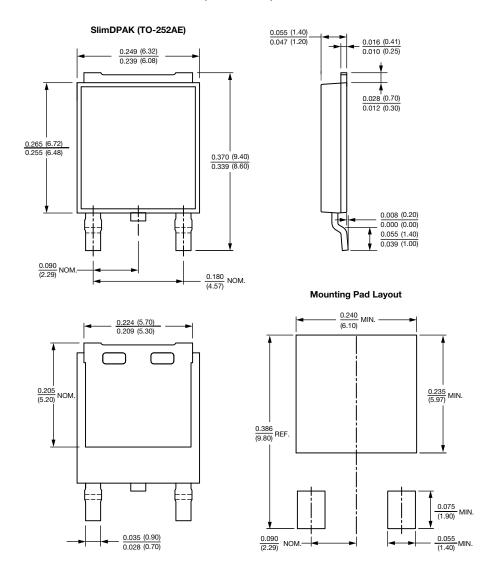


Fig. 7 - Typical Resistance Junction to Ambient vs. Copper Pad Areas

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





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